

**IN THE CLAIMS**

Amend the claims as follows:

1 – 17 (Cancelled).

18. (New) A surface mount composite electronic component, comprising a circuit element formed on a pair of opposed surfaces of an insulating substrate composed of a hexahedron, comprising electrodes that make up the circuit element which also function as external terminals.

19. (New) The surface mount composite electronic component according to claim 18, wherein the circuit element is composed of electrodes as well as resistors or dielectrics that contact said electrodes, a nickel plate layer and a solder plate layer laid down, in that order, on the surfaces of external terminal areas of said electrodes.

20. (New) The surface mount composite electronic component according to claim 18, wherein one surface of the insulating substrate is substantially perpendicular to an adjacent surface.

21. (New) The surface mount composite electronic component according to claim 18, having an area in which no electrodes are present on an edge portion of the surface of the insulating substrate on which said external terminals are present, disposed perpendicular to a

straight line connecting a pair of external terminals electrically connected to one circuit element.

22. (New) The surface mount composite electronic component according to claim 18, having an area in which the electrodes and the resistor overlap and contact each other on the surface of the insulating substrate, the resistor disposed on the insulating substrate in said area, and further, the electrodes laid on the resistor.

23. (New) The surface mount composite electronic component according to claim 18, wherein a relation between an insulating substrate dimension ( $L$ ) in a direction of flow of electric current of the circuit element of the insulating substrate surface on which circuit elements are formed, an insulating substrate dimension ( $T$ ) perpendicular to  $L$ , and a distance ( $W$ ) between surfaces of the insulating substrate on which the circuit elements are formed is  $L \geq W > T$ .

24. (New) The surface mount composite electronic component according to claim 18, wherein the electrodes that also function as external terminals are also present on a surface of the insulating substrate adjacent to the surface of the insulating substrate on which the circuit elements are present.

25. (New) A surface mount composite electronic component, comprising:  
a pair of first electrodes disposed on both ends of a front surface of an insulating substrate composed of a hexahedron and a first shared electrode disposed between and separate from said

first electrodes;

a pair of second electrodes disposed on a rear surface of the insulating substrate opposite the first electrodes and a second shared electrode disposed between and separate from said second electrodes;

two first resistors disposed so as to contact the first pair of electrodes and the first shared electrode; and

two second resistors disposed so as to contact the second pair of electrodes and the second shared electrode.

26. (New) The surface mount composite electronic component according to claim 25, wherein the number of external terminals is six.

27. (New) The surface mount composite electronic component according to claim 25, wherein the circuit element is composed of electrodes as well as resistors or dielectrics that contact said electrodes, a nickel plate layer and a solder plate layer laid down, in that order, on the surfaces of external terminal areas of said electrodes.

28. (New) The surface mount composite electronic component according to claim 25, wherein one surface of the insulating substrate is substantially perpendicular to an adjacent surface.

29. (New) The surface mount composite electronic component according to claim 25, having an area in which no electrodes are present on an edge portion of the surface of the insulating substrate on which said external terminals are present, disposed perpendicular to a straight line connecting a pair of external terminals electrically connected to one circuit element.

30. (New) The surface mount composite electronic component according to claim 25, having an area in which the electrodes and the resistor overlap and contact each other on the surface of the insulating substrate, the resistor disposed on the insulating substrate in said area, and further, the electrodes laid on the resistor.

31. (New) The surface mount composite electronic component according to claim 25, wherein a relation between an insulating substrate dimension (L) in a direction of flow of electric current of the circuit element of the insulating substrate surface on which circuit elements are formed, an insulating substrate dimension (T) perpendicular to L, and a distance (W) between surfaces of the insulating substrate on which the circuit elements are formed is  $L \geq W > T$ .

32. (New) The surface mount composite electronic component according to claim 25, wherein the electrodes that also function as external terminals are also present on a surface of the insulating substrate adjacent to the surface of the insulating substrate on which the circuit elements are present.

33. (New) A method of manufacturing a surface mount composite electronic component, comprising:

a step of forming predetermined circuit elements on both side surfaces of an insulating substrate of divisional units of a large-scale insulating substrate demarcated latitudinally and longitudinally on both side surfaces thereof at opposing locations; and

a step of dividing the large-scale insulating substrate into said divisional units,

a composite electronic component composed of circuit elements on both side surfaces of the insulating substrate being formed by these steps,

one of the surfaces of the insulating substrate other than the both side surfaces of the insulating substrate being a surface facing a circuit board.

34. (New) The surface mount composite electronic component according to claim 33, wherein formation of the insulating substrate surface facing the circuit board is accomplished by dicing.